

**Amendments to the Claims:**

The following listing of claims will replace all prior versions, and listings, of claims in the application:

1. (Currently Amended) An apparatus for mounting a plurality of semiconductor devices~~semiconductor device~~ on a wiring board, ~~which~~the apparatus comprising:

a compression bonding head relatively movable to a table on which the wiring board is placed;~~and~~ said compression bonding head having a holding means with a plurality of suction parts for sucking and holding pressing chips and said semiconductor devices thereon, wherein said suction parts are provided at the positions respectively corresponding to said semiconductor devices

~~— a press head provided with holding means whereby a pressing chip for forming a concave of a predetermined size in an insulating adhesive layer, which has been tentatively thermocompression bonded onto said wiring board, and said semiconductor device are held respectively.~~

2-3. (Canceled)

4. (Currently Amended) The apparatus as claimed in claim ~~4~~1, wherein said holding means are constructed as sucking the air via a suction hole formed in the compression bonding part of said compression bonding head.

5-10. (Canceled)